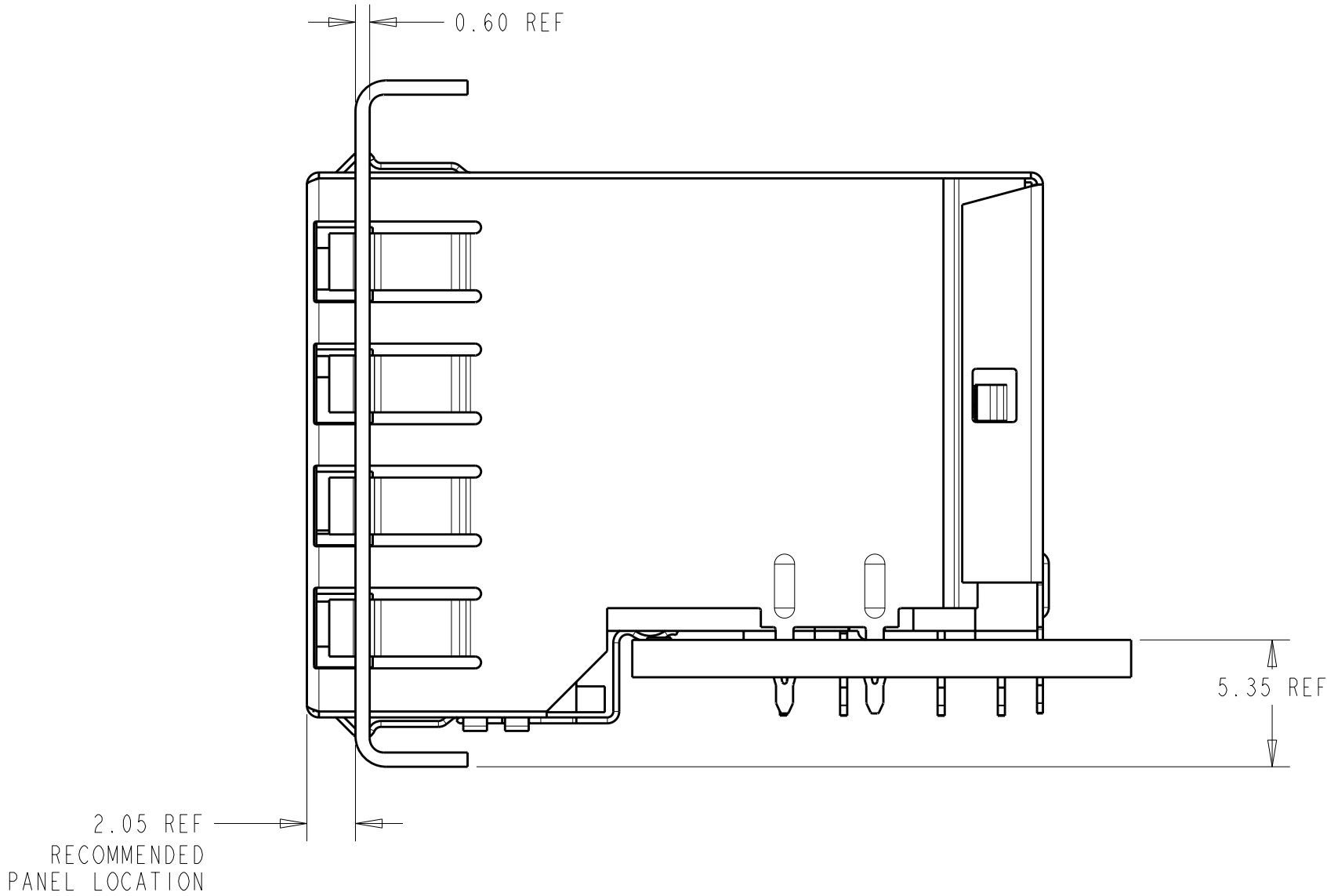
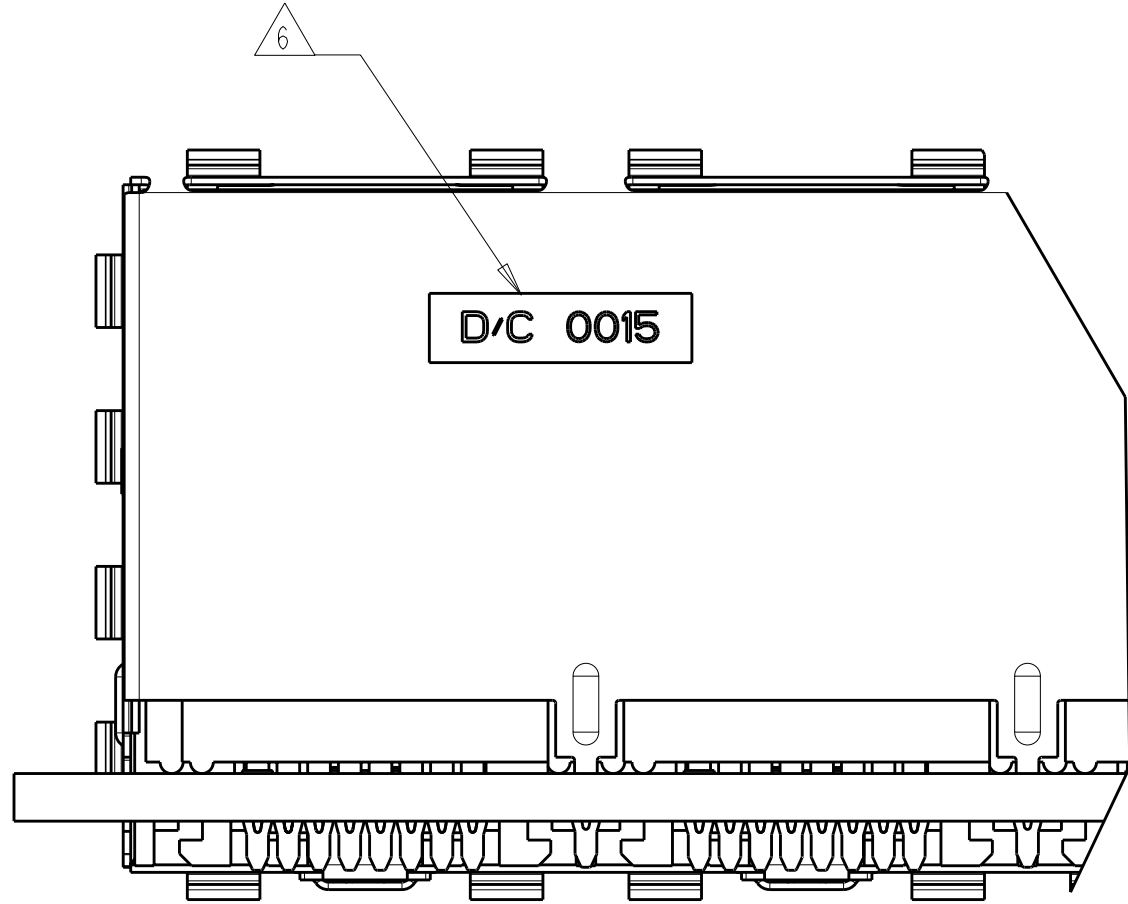


ATCA PANEL AND
PRINTED CIRCUIT BOARD
ASSEMBLY LAYOUT



AMC PANEL AND
PRINTED CIRCUIT BOARD
ASSEMBLY LAYOUT

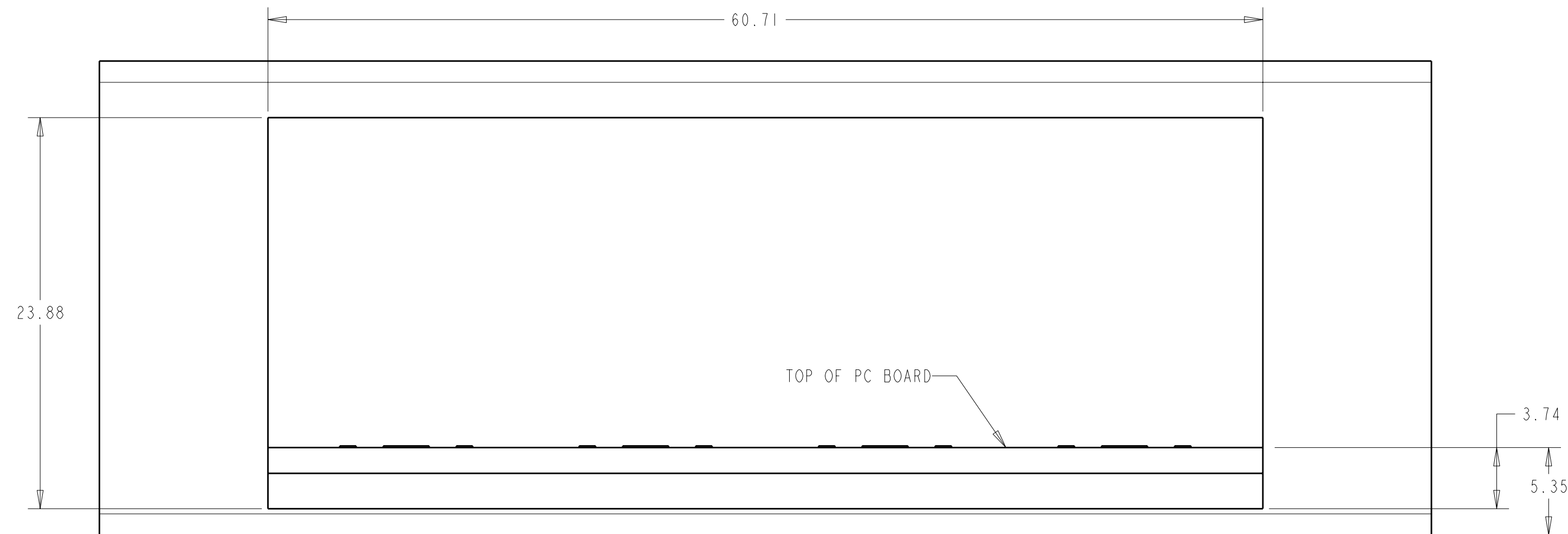
LOC		DIST		REVISIONS					
AA		00		P	LTR	DESCRIPTION	DATE	DWN	APVD
				A		RELEASED	21OCT2006	LAM	JW
				B		ECO-07-001858	29JAN2007	LAM	JW
				C		ECO-07-008800	18APR2007	LAM	JW
				D		ECR-08-019486	04AUG2008	A.L	S.Y



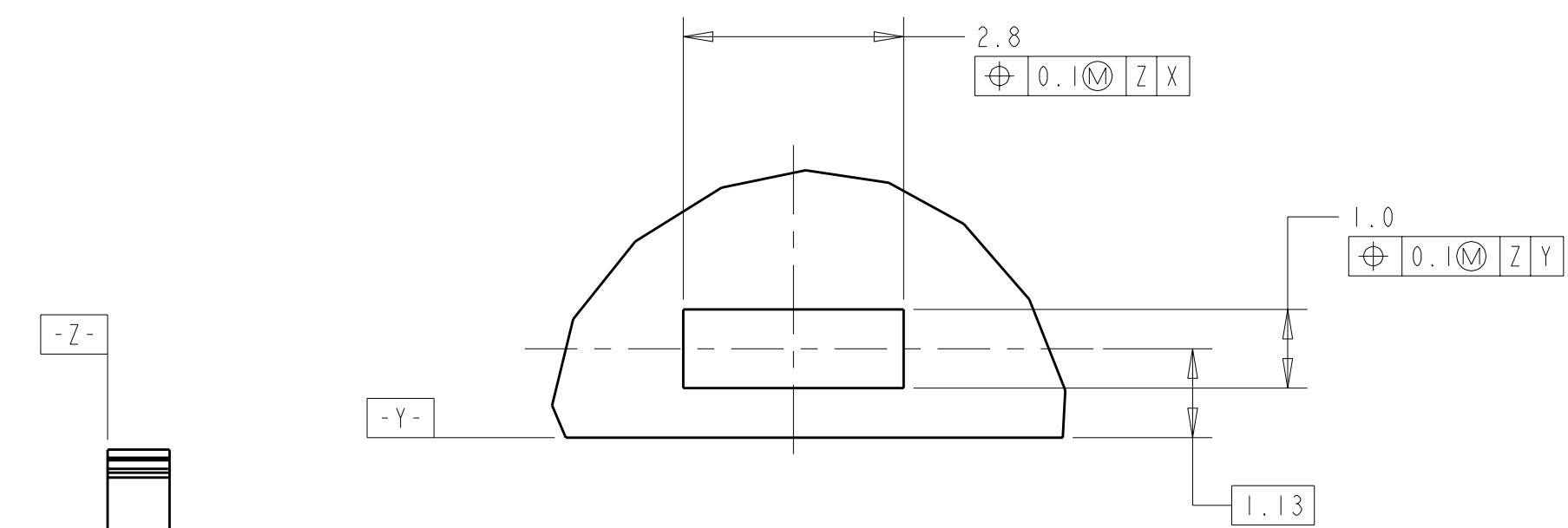
1. MATERIAL:
HOUSING:
PBT POLYESTER, BLACK, UL 94V-0
TERMINALS:
0.33 THICK PHOSPHOR BRONZE PLATED WITH 1.27µm MINIMUM THICK
HARD GOLD IN LOCALIZED AREA AND 2.0µm MINIMUM THICK
MATTE TIN IN COMPLIANT PIN TERMINAL AREA
OVER 1.27µm MINIMUM THICK NICKEL UNDERPLATE
SHIELD:
0.25 THICK COPPER ALLOY PLATED WITH 2.03µm MINIMUM TIN
OVER 1.27 µm MINIMUM NICKEL
GROUND CLIP: 0.25 THICK COPPER ALLOY PRE-PLATED WITH 2.03µm
MINIMUM MATTE TIN OVER 1.27µm MINIMUM NICKEL
2. JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68
SUBPART F.
3. MAXIMUM PIN LENGTH 3.40 FROM TOP SURFACE OF PC BOARD
4. FINISHED PLATED THROUGH HOLE DIAMETER - ANNULAR RING
DIAMETER 1.3 TO 1.5
5. DATUMS AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER
6. DATE CODE LOCATED ON REAR OF PART APPROXIMATELY AS SHOWN
7. CONTACTS ARE NOT INTENDED TO BE ALIGNED WITH EACH OTHER

15.88	WITH GROUND CLIP	1888506-2 (SHOWN)
16.13	WITHOUT GROUND CLIP	1888506-1
M DIM	DESCRIPTION	PART NUMBER

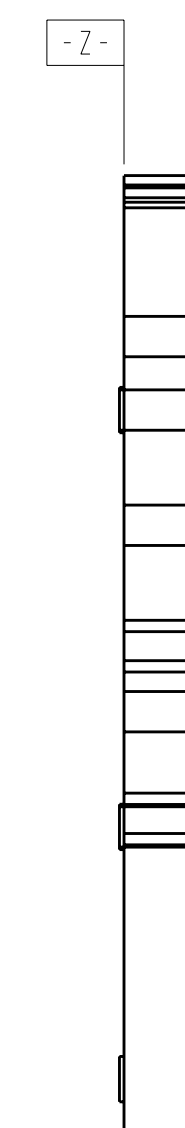
TYPICAL DIMENSIONS TO CENTERLINE UNLESS OTHERWISE SPECIFIED TYPICAL DIMENSIONS TO CENTERLINE UNLESS OTHERWISE SPECIFIED TYPICAL DIMENSIONS TO CENTERLINE UNLESS OTHERWISE SPECIFIED		DWN L.A.MAYER 21OCT2006	Tyco Electronics Corporation Harrisburg, PA 17105-3608	
DIMENSIONS: mm		CHK J.WESTMAN 21OCT2006	NAME STACKED MOD JACK ASSEMBLY, 2 X 4, 8 POSN, RJ45, SHIELDED, PANEL GROUND, OFFSET, CAT 5	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD S.CLICKINGER 21OCT2006	SIZE A1	
9 PLC ±.1		PRODUCT SPEC	CAGE CODE 00779	
1 PLC ±.13		APPLICATION SPEC	DRAWING NO C=1888506	
3 PLC ±.1		WEIGHT	RESTRICTED TO	
4 PLC ±.1		FINISH	CUSTOMER DRAWING	
ANGLES ±1°			SCALE 4:1	
MATERIAL SEE NOTE 1			SHEET 1 OF 2	
			REV D	




AMC PANEL AND PRINTED CIRCUIT BOARD LAYOUT



PC BOARD LAYOUT (COMPONENT SIDE)



THIS DRAWING IS A CONTROLLED DOCUMENT FOR THE CUSTOMER'S INFORMATION. IT IS SUBJECT TO THE SAME CONTROLS AS THE ORGANIZATION'S DOCUMENTS. IT SHOULD BE CONTACTED FOR THE LATEST REVISION.		DWN L. A. MAYER 210CT2006		Tyco Electronics Corporation	
DIMENSIONS:		C/KH WESTMAN 210CT2006		Harrisburg, PA 17105-3608	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD S. FLICKINGER 210CT2006		NAME	
mm		PRODUCT SPEC		STACKED MOD JACK ASSEMBLY, 2 X 4,	
		108-1854		8 POSN, RJ45, SHIELDED, PANEL	
0 PLC ±. 1 PLC ±. 2 PLC ±.013 4 ANGLES ±. 4 ANGLES ±.1		APPLICATION SPEC		GROUND, OFFSET, CAT 5	
MATERIAL		114-2160		SIZE	
FINISH		WEIGHT		CAGE CODE	
SEE NOTE 1		-		DRAWING NO	
		CUSTOMER DRAWING		A1 00779 C=1888506	
				RESTRICTED TO	
				-	
				SCALE 1:1 SHEET 2 OF 2 REV D	

Mouser Electronics

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[TE Connectivity:](#)

[1888506-1](#)